

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ440N10NS3 G	**Issued**	16. January 2020
MA#	MA001583326		
Package	PG-TSDSON-8-1	**Weight***	36.14 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.830	2.30	2.30	22961	22961
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5239	
	non noble metal	copper	7440-50-8	7.689	21.27	21.83	212743	218309
wire	non noble metal	copper	7440-50-8	0.040	0.11	0.11	1102	1102
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1030	
	plastics	epoxy resin	-	1.918	5.31		53071	
	inorganic material	silicondioxide	60676-86-0	16.667	46.13	51.54	461150	515251
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10239	10239
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2236	2236
solder	non noble metal	tin	7440-31-5	0.023	0.06		624	
	noble metal	silver	7440-22-4	0.028	0.08		780	
	non noble metal	lead	7439-92-1	1.078	2.98	3.12	29814	31218
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2168	
	non noble metal	copper	7440-50-8	3.182	8.80	9.03	88036	90339
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2600	
	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105582	108345
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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